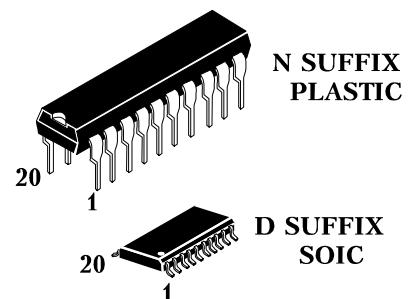


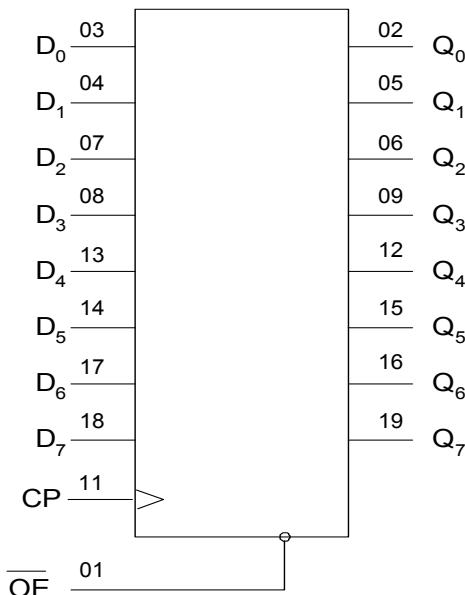
## OCTAL D-TYPE FLIP-FLOP POSITIVE EDGE-TRIGGER (3-STATE)

IN74LV374 are compatible by pinning with KP555ИР23, KP1533ИР13, IN74HC374A and IN74HCT374A series. Input voltage levels are compatible with standard CMOS levels.

- Output voltage levels are compatible with input levels of CMOS, NMOS and TTL ICs.
- Supply voltage range from 2.0 to 3.2 V
- LOW input current: 1.0  $\mu$ A; 0.1  $\mu$ A at  $T = 25^\circ\text{C}$
- Output current 8 mA
- Latch current value not less than 150 mA at  $T = 125^\circ\text{C}$
- ESD acceptable values: not less than 2000 V as per HBM, and not less than 200 V as per MM

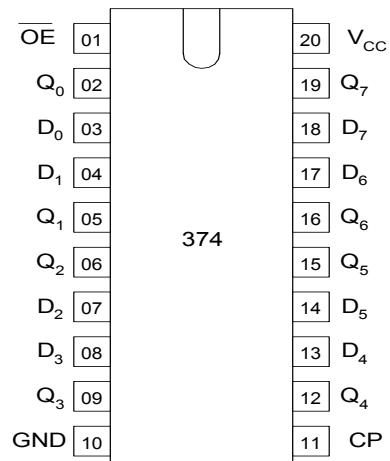


### BLOCK DIAGRAM



Pin 20=V<sub>CC</sub>  
Pin 10 = GND

### PIN ASSIGNMENT



### FUNCTION TABLE

Inputs		Output	
OE	CP	D <sub>n</sub>	Q <sub>n</sub>
L	↑	H	H
L	↑	L	L
L	L, H, Z	X	no change
H	X	X	Z

# IN74LV374

## ABSOLUTE MAXIMUM RATINGS\*

Symbol	Parameter	Rating	Unit
$V_{CC}$	Supply voltage	-0.5 to +5.0	V
$I_{IK}^{*1}$	Input diode current	$\pm 20$	mA
$I_{OK}^{*2}$	Output diode current	$\pm 50$	mA
$I_O^{*3}$	Output source or sink current	$\pm 35$	mA
$I_{CC}$	Bus driver outputs	$\pm 70$	mA
$I_{GND}$	Ground current	$\pm 70$	mA
$P_D$	Power dissipation per package, Plastic DIP <sup>*4</sup> SOIC <sup>*4</sup>	750 500	mW
Tstg	Storage temperature range	-65 to +150	°C

\* In absolute maximum ratings modes functioning is not guaranteed. Upon lifting the absolute maximum ratings functioning is guaranteed at the recommended operating conditions.

<sup>\*1</sup> Provide  $V_I < -0.5$  V or  $V_I > V_{CC} + 0.5$  V.

<sup>\*2</sup> Provide  $V_O < -0.5$  V or  $V_O > V_{CC} + 0.5$  V.

<sup>\*3</sup> Provide  $-0.5$  V <  $V_O$  <  $V_{CC} + 0.5$  V.

<sup>\*4</sup> When operating in the temperature range of 70°C to 125°C power dissipation value decreases  
- for Plastic DIP by 12 mW/°C  
- for SOIC by 8 mW/°C

## RECOMMENDED OPERATING MODES

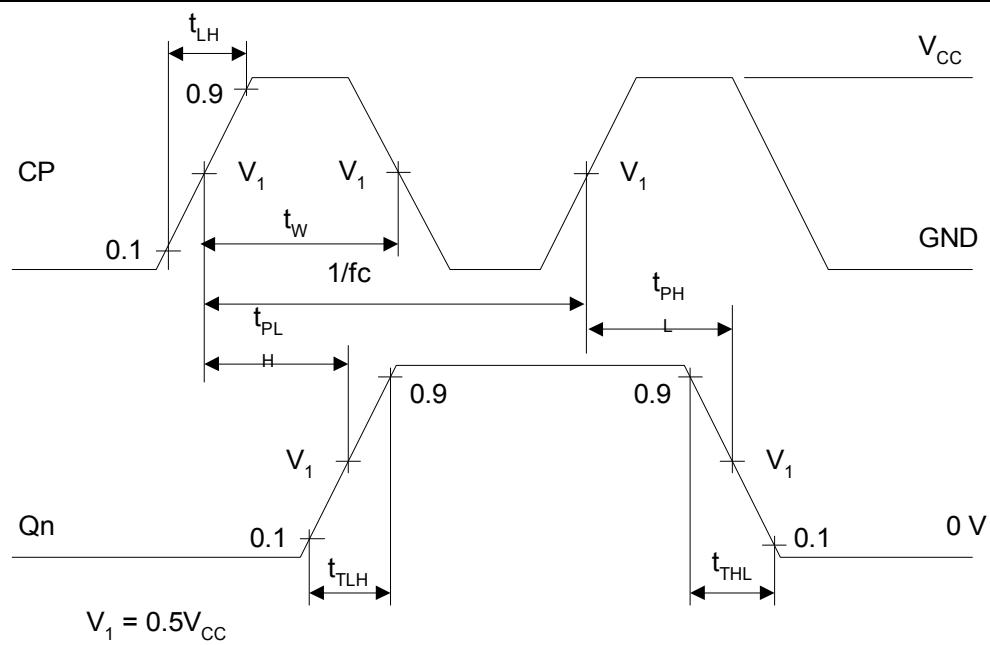
Symbol	Parameter	Min	Max	Unit
$V_{CC}$	Supply voltage	1.2	3.6	V
$V_{IN}$	Input voltage	0	$V_{CC}$	V
$V_{OUT}$	Output voltage	0	$V_{CC}$	V
$T_A$	Operating ambient temperature range. For all types packages	-40	125	°C
$t_{LH}, t_{HL}$	Input rise and fall times $V_{CC} = 1.2$ V $V_{CC} = 2.0$ V $V_{CC} = 3.0$ V $V_{CC} = 3.6$ V	0	1000 700 500 400	ns

## DC CHARACTERISTICS

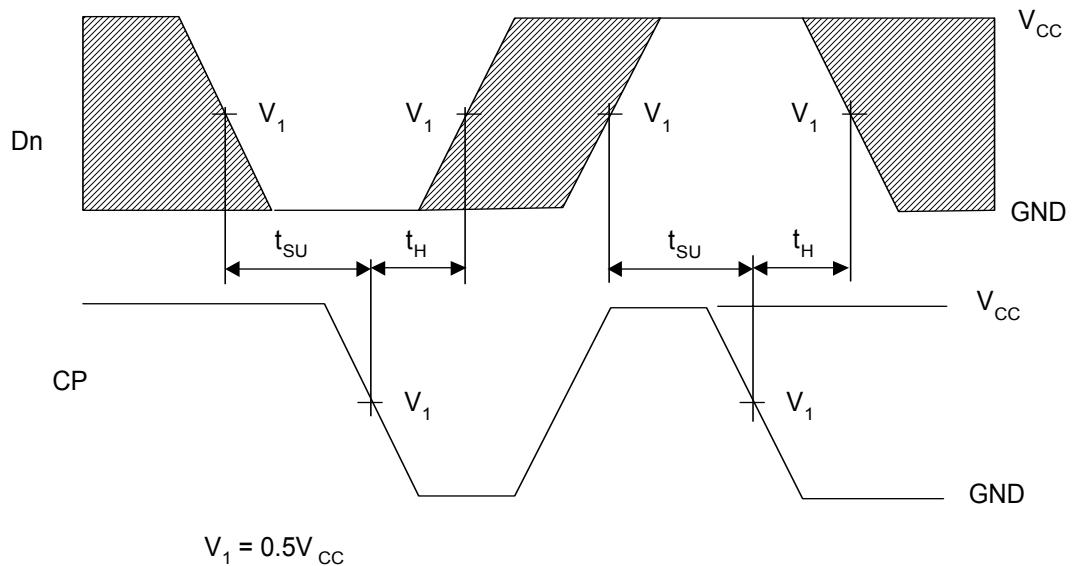
Symbol	Parameter	Test conditions	V <sub>CC</sub> , V	Limits						Unit	
				25°C		-40°C to 85°C		125°C			
				min	max	min	max	min	max		
V <sub>IH</sub>	HIGH level input voltage	V <sub>O</sub> = V <sub>CC</sub> -0.1 V	1.2 2.0 3.0 3.6	0.9 1.4 2.1 2.5	- - - -	0.9 1.4 2.1 2.5	- - - -	0.9 1.4 2.1 2.5	- - - -	V	
V <sub>IL</sub>	LOW level input voltage	V <sub>O</sub> = 0.1 V	1.2 2.0 3.0 3.6	- - - -	0.3 0.6 0.9 1.1	- - - -	0.3 0.6 0.9 1.1	- - - -	0.3 0.6 0.9 1.1	V	
V <sub>OH</sub>	HIGH level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>O</sub> = -50 μA	1.2 2.0 3.0 3.6	1.1 1.92 2.92 3.52	- - - -	1.0 1.9 2.9 3.5	- - - -	1.0 1.9 2.9 3.5	- - - -	V	
		V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>O</sub> = -8 mA	3.0	2.48	-	2.34	-	2.20	-	V	
V <sub>OL</sub>	LOW level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>O</sub> = 50 μA	1.2 2.0 3.0 3.6	- - - -	0.09 0.09 0.09 0.09	- - - -	0.1 0.1 0.1 0.1	- - - -	0.1 0.1 0.1 0.1	V	
		V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>O</sub> = 8 mA	3.0	-	0.33	-	0.4	-	0.5	V	
I <sub>I</sub>	Input leakage current	V <sub>I</sub> = V <sub>CC</sub> или 0 V	3.6	-	±0.1	-	±1.0	-	±1.0	μA	
I <sub>OZ</sub>	Output OFF-state current	3-state outputs V <sub>I</sub> = V <sub>IL</sub> or V <sub>IH</sub> V <sub>O</sub> = V <sub>CC</sub> or 0 V	3.6	-	±0.5	-	±5	-	±10	μA	
I <sub>CC</sub>	Supply current	V <sub>I</sub> = V <sub>CC</sub> or 0 V I <sub>O</sub> = 0 μA	3.6	-	8.0	-	80	-	160	μA	

AC CHARACTERISTICS ( $C_L = 50 \text{ pF}$ ,  $t_{LH} = t_{HL} = 6.0 \text{ ns}$ )

Symbol	Parameter	Test conditions	$V_{CC}, \text{V}$	Limits						Unit	
				25°C		-40°C to 85°C		125°C			
				min	max	min	max	min	max		
$t_{PHL}, t_{PLH}$ from CP to Qn	Propagation delay	Figure 1	1.2 2.0 3.0	- - -	180 45 27	- - -	230 56 34	- - -	270 68 41	ns	
$t_{PHZ}, t_{PLZ}$ from OE to Qn	Propagation delay	Figure 3	1.2 2.0 3.0	- - -	160 38 25	- - -	200 57 36	- - -	240 68 43		
$t_{PZH}, t_{PZL}$ from OE to Qn	Propagation delay	Figure 3	1.2 2.0 3.0	- - -	160 38 23	- - -	200 48 29	- - -	240 58 35		
$t_{THL}, t_{TLH}$	HIGH-to-LOW and LOW-to-HIGH transition time	Figure 1	1.2 2.0 3.0	- - -	75 16 10	- - -	100 20 13	- - -	120 24 15		
$t_W$	Clock pulse width HIGH or LOW	Figure 1	1.2 2.0 3.0	250 18 11	- - -	350 23 14	- - -	540 28 17	- - -		
$t_{SU}$	Set-up time Dn to CP	Figure 2	1.2 2.0 3.0	45 13 8	- - -	50 17 10	- - -	100 20 12	- - -		
$t_H$	Hold time Dn to CP	Figure 2	1.2 2.0 3.0	25 5 5	- - -	25 5 5	- - -	25 5 5	- - -		
$f_C$	CP maximum pulse frequency	Figure 1	2.0 3.0	- -	27 46	- -	22 37	- -	18 31	MHz	
$C_I$	Input capacitance		3.0	-	7	-	-	-	-	pF	
$C_{PD}$	Power dissipation capacitance (per flip-flop)	$V_I = 0 \text{ V}$ or $V_{CC}$	3.0	-	34	-	-	-	-		



**Figure 1- Time diagram**



**Figure 2 - Time diagram**

# IN74LV374

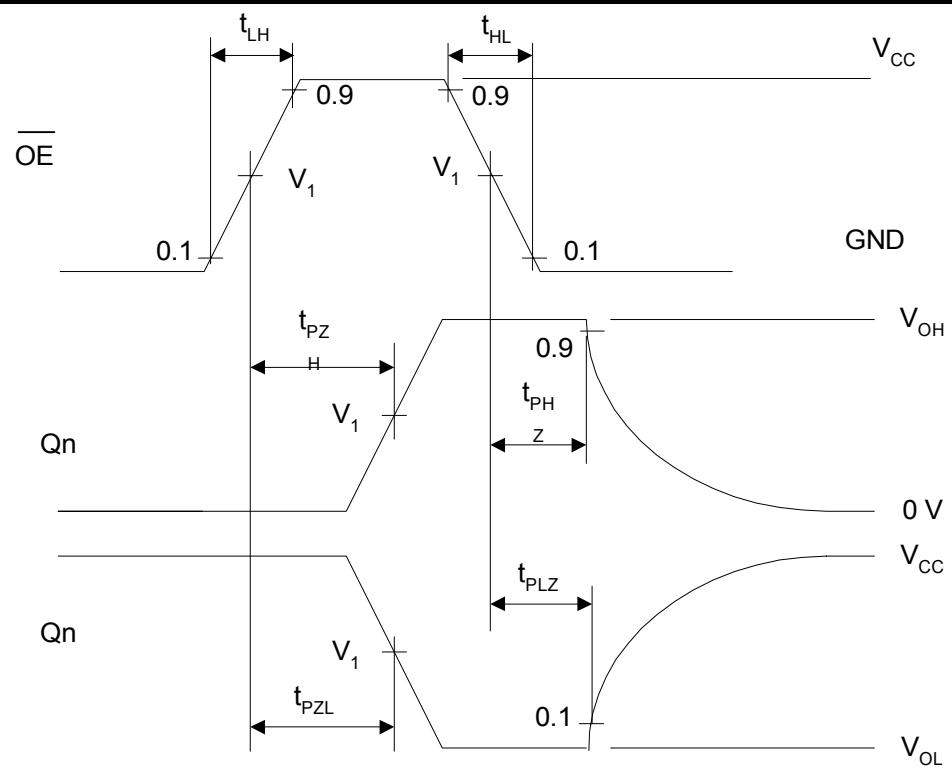
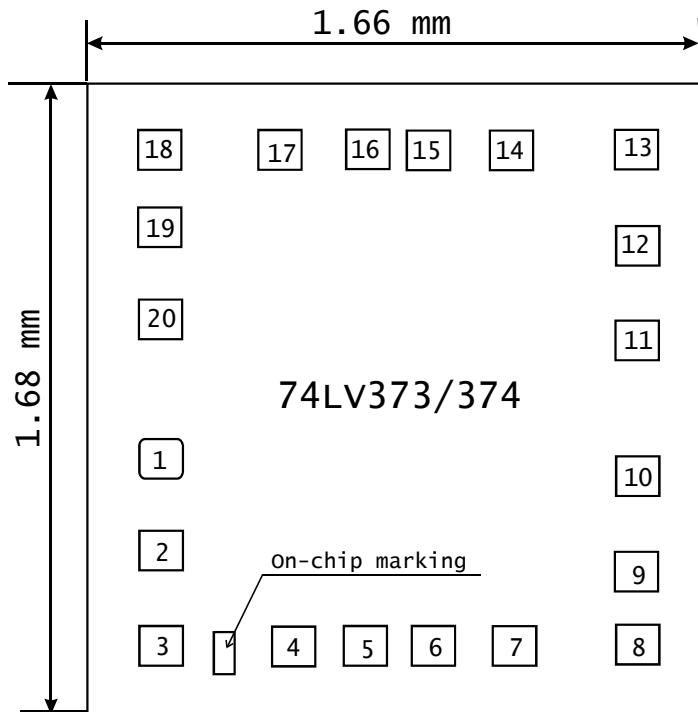


Figure 3 - Time diagram

# IN74LV374

## Drawing of the chip



Pads allocation Table

Pad number	coordinates (counted from lower left corner), mm		Pad size, mm
	X	Y	
01	0.142	0.628	0.108 x 0.108
02	0.142	0.377	0.108 x 0.108
03	0.142	0.125	0.108 x 0.108
04	0.498	0.125	0.108 x 0.108
05	0.693	0.125	0.108 x 0.108
06	0.871	0.125	0.108 x 0.108
07	1.095	0.125	0.108 x 0.108
08	1.423	0.130	0.108 x 0.108
09	1.423	0.329	0.108 x 0.108
10	1.423	0.587	0.108 x 0.108
11	1.423	0.949	0.108 x 0.108
12	1.423	1.198	0.108 x 0.108
13	1.423	1.447	0.108 x 0.108
14	1.085	1.447	0.108 x 0.108
15	0.868	1.447	0.108 x 0.108
16	0.696	1.447	0.108 x 0.108
17	0.461	1.447	0.108 x 0.108
18	0.142	1.447	0.108 x 0.108
19	0.142	1.245	0.108 x 0.108
20	0.142	0.997	0.108 x 0.108